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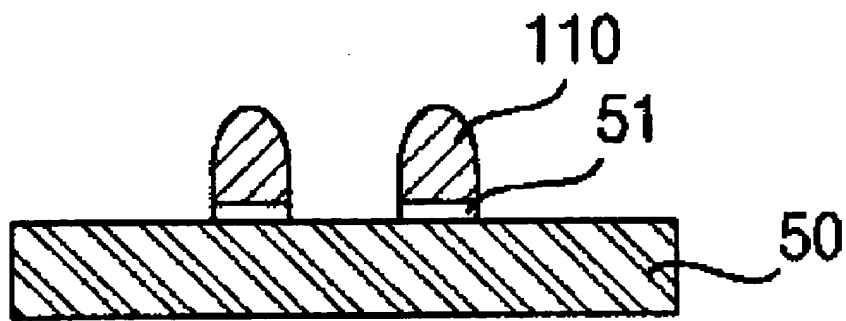
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TITLE: Direct interconnection method between bare chip  
semiconductor integrated circuit and circuit substrate  
pattern

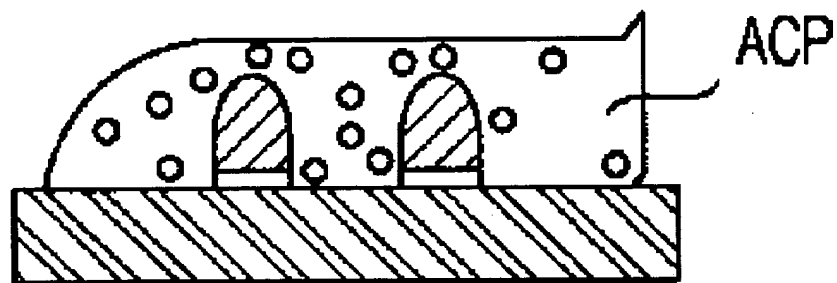
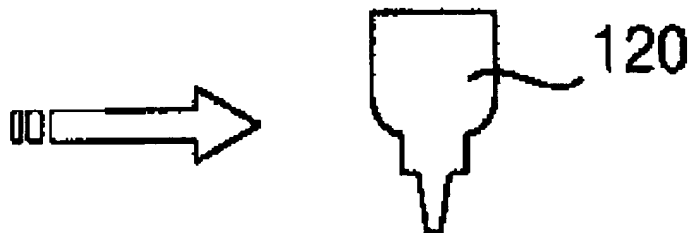
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Basic Abstract Text - ABTX (2):

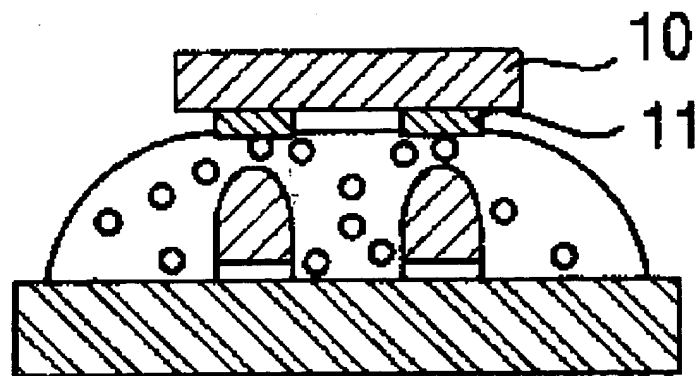
DETAILED DESCRIPTION - In the method, contrary to a conventional stud bump formed directly on the bare chip circuit, the bump(110) is formed on the pattern(51) of a circuit substrate(50) by using a solder ball. Therefore, the damage of the bare chip circuit is prevented and a conventional **UBM process is not required**. Next, the circuit substrate(50) having the bump(110) is coated with an anisotropic conductive paste(ACP) by using a syringe(120). Then, the bare chip(10) having an aluminum electrode(11) is mounted on the circuit substrate(50) while aligning the aluminum electrode(11) with the bump(110).



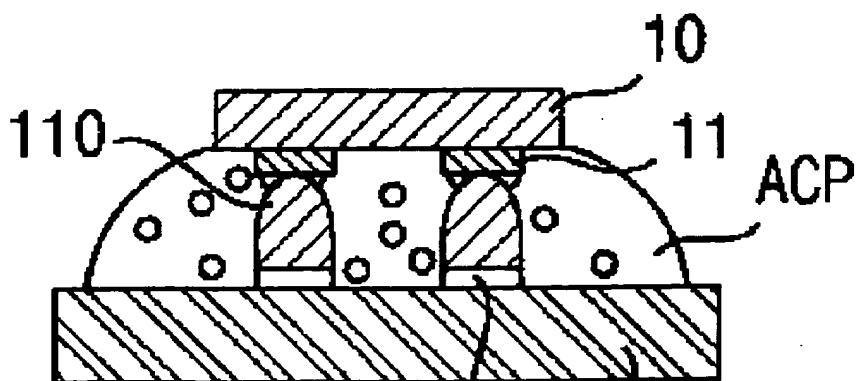
회로기판 위에 Soid Ball을 이용 Bump형.



ACP Dispensing



IC Mounting



경화